



Product Change Notification

113275 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #: 113275 - 00
Change Title: Intel® SSD DC S3500 Series (80GB, 120GB, 160GB, 240GB, 300GB, 400GB, 480GB, 600GB, 800GB) 2.5"
Intel® SSD DC S3500 Series (80GB, 240GB, 400GB, 800GB) 1.8"
Intel® SSD DC S3700 Series (100GB, 200GB, 400GB, 800GB) 2.5"
PCN 113275-00
Product Design
Update ASIC Mold Compound
Date of Publication: October 16, 2014

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	Dec 01, 2014
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Description of Change to the Customer:

Intel is upgrading SSD Controller assembly mold compound for S3700 and S3500 to G750SE to match S3500 M2/HD. The new mold compound provides better co-planarity performance.

Customer Impact of Change and Recommended Action:

Since the ASIC mold compound update has incremental improvement over the previous version, Intel performed component qualification and anticipates no product impact with this new mold compound.

Intel will attempt to deplete pre-conversion material before shipping post-conversion material but there is a possibility of Intel shipping mixed inventory. Therefore, customers will need to manage and migrate to the post-conversion material as soon as possible.

Milestone dates are estimates and subject to change based on business and operational conditions.

Products Affected / Intel Ordering Codes:

Product Code	MM#
SSDSC2BA100G301921632	921632
SSDSC2BA200G301921634	921634
SSDSC2BA400G301921636	921636
SSDSC2BA800G301921638	921638
SSDSC1NA200G301922137	922137
SSDSC1NA400G301922138	922138
SSDSC2BA100G3 925878	925878
SSDSC2BA200G3 925879	925879
SSDSC2BA400G3 925880	925880
SSDSC2BA800G3 925882	925882
SSDSC1NB080G401927191	927191
SSDSC1NB240G401927192	927192
SSDSC1NB400G401927193	927193
SSDSC1NB080G4 927194	927194
SSDSC1NB240G4 927195	927195
SSDSC1NB400G4 927196	927196
SSDSC2BB080G401927197	927197
SSDSC2BB120G401927198	927198
SSDSC2BB160G401927199	927199
SSDSC2BB240G401927200	927200
SSDSC2BB300G401927201	927201
SSDSC2BB480G401927202	927202
SSDSC2BB800G401927204	927204
SSDSC2BB080G4 927205	927205
SSDSC2BB120G4 927206	927206
SSDSC2BB160G4 927207	927207
SSDSC2BB240G4 927208	927208
SSDSC2BB300G4 927209	927209
SSDSC2BB480G4 927210	927210
SSDSC2BB800G4 927211	927211
SSDSC1NB800G4 927436	927436
SSDSC1NB800G401927441	927441
SSDSC2BB600G401928390	928390
SSDSC1NA200G3 929439	929439
SSDSC1NA400G3 929440	929440
SSDSC2BB600G4 930361	930361

PCN Revision History:

Date of Revision:

October 16, 2014

Revision Number:

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Reason:

Originally Published PCN